

ABSTRACT

5 An adhesive tape for semiconductor, including a film-like adhesive and a pressure-sensitive adhesive tape laminated to the film-like adhesive, wherein the film-like adhesive contains an epoxy resin and a curing agent, the epoxy resin includes an epoxy resin that is liquid at 25 °C, and a number-average molecular weight of the epoxy resin that is liquid at 25 °C is 350 or more.

No Suitable Figure.